



**CHENMKO ENTERPRISE CO.,LTD**

**2N7002EGP**

**SURFACE MOUNT**

**N-Channel Enhancement Mode Field Effect Transistor**

VOLTAGE 60 Volts CURRENT 115 mAmpere

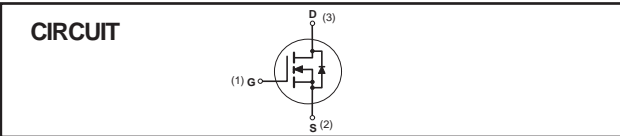
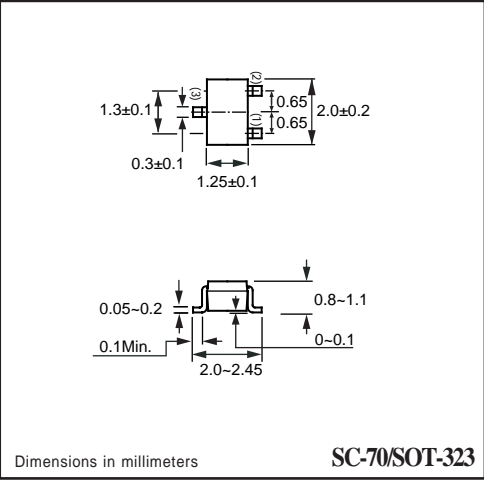
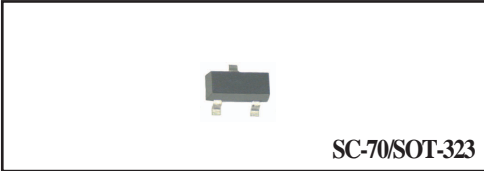
Halogens free devices

**APPLICATION**

- \* Servo motor control.
- \* Power MOSFET gate drivers.
- \* Other switching applications.

**FEATURE**

- \* Small surface mounting type. (SC-70/SOT-323)
- \* High density cell design for low  $R_{DS(ON)}$ .
- \* Suitable for high packing density.
- \* Rugged and reliable.
- \* High saturation current capability.
- \* Voltage controlled small signal switch.



**Absolute Maximum Ratings**  $T_A = 25^\circ\text{C}$  unless otherwise noted

| Symbol    | Parameter   | 2N7002EGP  | Units            |
|-----------|---|------------|------------------|
| $V_{DSS}$ | Drain-Source Voltage  | 60         | V                |
| $V_{GSS}$ | Gate-Source Voltage   | $\pm 20$   | V                |
| $I_D$     | Maximum Drain Current - Continuous $T_A = 25^\circ\text{C}$ | 115        | mA               |
| $P_D$     | Maximum Power Dissipation $T_A = 25^\circ\text{C}$          | 200        | mW               |
| $T_J$     | Operating Temperature Range                                 | -55 to 150 | $^\circ\text{C}$ |
| $T_{STG}$ | Storage Temperature Range                                   | -55 to 150 | $^\circ\text{C}$ |

**Thermal characteristics**

|                 |  |     |                    |
|-----------------|--|-----|--------------------|
| $R_{\theta JA}$ | Thermal Resistance, Junction-to-Ambient (Note 1) | 625 | $^\circ\text{C/W}$ |
|-----------------|--|-----|--------------------|

## ELECTRICAL CHARACTERISTIC ( 2N7002EGP )

**Electrical Characteristics**  $T_A = 25^\circ\text{C}$  unless otherwise noted

| Symbol | Parameter | Conditions | Min | Typ | Max | Units |
|--------|-----------|------------|-----|-----|-----|-------|
|--------|-----------|------------|-----|-----|-----|-------|

### OFF CHARACTERISTICS

|            |                                 |  |                           |  |     |               |
|------------|---------------------------------|--|---------------------------|--|-----|---------------|
| $BV_{DSS}$ | Drain-Source Breakdown Voltage  | $V_{GS} = 0\text{ V}, I_D = 10\ \mu\text{A}$ | 60                        |  |     | V             |
| $I_{DSS}$  | Zero Gate Voltage Drain Current | $V_{DS} = 60\text{ V}, V_{GS} = 0\text{ V}$  |                           |  | 1   | $\mu\text{A}$ |
|            |                                 |  | $T_J = 125^\circ\text{C}$ |  |     | 0.5           |
| $I_{GSSF}$ | Gate - Body Leakage, Forward    | $V_{GS} = 15\text{ V}, V_{DS} = 0\text{ V}$  |                           |  | 10  | nA            |
| $I_{GSSR}$ | Gate - Body Leakage, Reverse    | $V_{GS} = -15\text{ V}, V_{DS} = 0\text{ V}$ |                           |  | -10 | nA            |

### ON CHARACTERISTICS (Note 1)

|              |                                   |   |                          |      |     |          |
|--------------|-----------------------------------|---|--------------------------|------|-----|----------|
| $V_{GS(th)}$ | Gate Threshold Voltage            | $V_{DS} = V_{GS}, I_D = 250\ \mu\text{A}$       | 1.0                      | 1.5  | 2.0 | V        |
| $R_{DS(on)}$ | Static Drain-Source On-Resistance | $V_{GS} = 5\text{ V}, I_D = 50\text{ mA}$       |                          | 3.2  | 7.5 | $\Omega$ |
|              |                                   | $V_{GS} = 10\text{ V}, I_D = 500\text{ mA}$     | $T_C = 25^\circ\text{C}$ |      | 4.4 |          |
| $I_{D(on)}$  | On-State Drain Current            | $V_{GS} = 10\text{ V}, V_{DS} = 7.5 V_{DS(on)}$ | 500                      | 1000 |     | mA       |
| $g_{FS}$     | Forward Transconductance          | $V_{DS} = 10\text{ V}, I_D = 200\text{ mA}$     | 80                       |      |     | mS       |

### DYNAMIC CHARACTERISTICS

|            |                              |   |  |     |    |             |
|------------|------------------------------|---|--|-----|----|-------------|
| $C_{iss}$  | Input Capacitance            | $V_{DS} = 25\text{ V}, V_{GS} = 0\text{ V},$<br>$f = 1.0\text{ MHz}$  |  | 22  | 50 | $\text{pF}$ |
| $C_{oss}$  | Output Capacitance           |   |  | 11  | 25 |             |
| $C_{riss}$ | Reverse Transfer Capacitance |   |  | 2.0 | 5  |             |
| $t_{on}$   | Turn-On Time (Note 4)        | $V_{DD} = 30\text{ V}, R_L = 150\ \Omega,$<br>$I_D = 200\text{ mA}, V_{gen} = 10\text{ V},$<br>$R_{GEN} = 25\ \Omega$ |  | 7.0 | 20 | $\text{nS}$ |
| $t_r$      | Turn-Off Time (Note 4)       |   |  | 11  | 20 |             |

Note:

1. Pulse Test: Pulse Width  $\leq 300\ \mu\text{s}$ , Duty Cycle  $\leq 2.0\%$ .

# RATING CHARACTERISTIC CURVES ( 2N7002EGP )

## Typical Electrical Characteristics

Figure 1. Output Characteristics

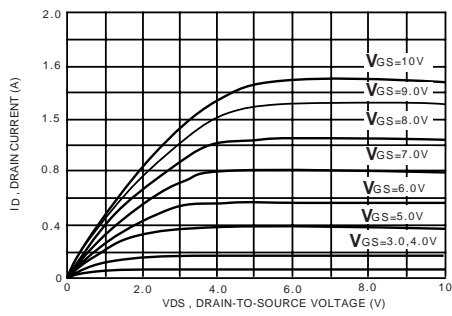


Figure 2. Transfer Characteristics

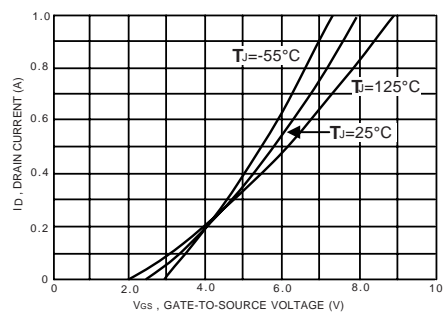


Figure 3. On-Resistance Variation with Temperature

